





Products Industries

Resources

About TE

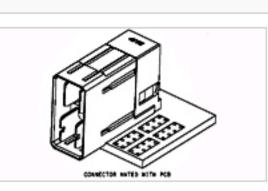
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Innovation

Support Center

Home > Products > Two-Piece High-Speed Connectors > Product Feature Selector > Product Details

2169869-4 Product Details



Impact High Density Backplane Connectors

IMP,PWR,5PR,R/A,Hdr,5.7,6.9,Tin

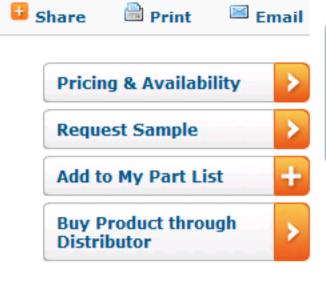
2169869-4

TE Internal Number: 2169869-4

Active

Product Highlights View All

- · Connector Style = Header
- 16/Power
- 32 Positions
- Header Type = Partially Shrouded
- Board-to-Board Configuration = Right Angle



Related Products

View Part in Product **Feature Selector**

Check for Tooling

Not quite the product you're looking for? **Find Similar Products**

ocuments Features	Compliance
lease Note: se the Product Drawing for all	design activity
Product Type Features	
PCB Mount Retention Type	Action/Compliant Tail
Electrical Characteristic	cs
Operating Voltage Reference	AC rms, DC
Operating Voltage (VAC)	250
Operating Voltage (VDC)	250
Dimensions	
Stack Height (mm [in])	22.80 [0.897]
Γail Length (mm [in])	2.5 [0.098]
ength (X-Axis) (mm in])	32.10 [1.2637]
Width (Z-Axis) (mm [in])	11.00 [0.433]
Profile Height (Y-Axis) (mm [in])	22.80 [0.8976]
PCB Hole Diameter (mm [in])	0.725 [0.0285]
Body Features	
Header Type	Partially Shrouded
Contact Features	
Contact Type	Pin
Contact Length (mm [in])	5.70 [0.224], 6.90 [0.271]
Contact Plating, Fermination Area,	Matte Tin

Configuration Features	
Connector Contact Configuration (No. of Pos./Type)	16/Power
Number of Positions ?	32
Number of Columns	2
Number of Rows ?	8
Tail Orientation	In-line
Industry Standards	
RoHS/ELV Compliance	RoHS compliant, ELV compliant
Lead Free Solder Processes ?	Not relevant for lead free process
RoHS/ELV Compliance History	Always was RoHS compliant
UL Rating	Recognized
UL File Number	E28476
UL Flammability Rating	UL 94V-0
CSA Certified	Yes
Environmental	
Operating Temperature (°C [°F])	-55 - +85 [-67 - +185]
	-55 - +85 [-67 - +185]
Temperature (°C [°F])	-55 - +85 [-67 - +185] Right Angle
Temperature (°C [°F]) Conditions for Usage Board-to-Board	
Temperature (°C [°F]) Conditions for Usage Board-to-Board Configuration	
Temperature (°C [°F]) Conditions for Usage Board-to-Board Configuration Operation/Application	Right Angle Networking

Corporate Information

Contact Plating, Termination Area,

Thickness (µm [µin])

Contact Base Material

Underplate Material

Underplate Material

Housing Features

Connector Style

Housing Material

Housing Color

Thickness (µm [µin])

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Site Map

LCP (Liquid Crystal

2.54 [100]

Nickel

Header

Black

Polymer)

Copper Alloy

1.27 [50.000]

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